

Balluff Wafer Mapping Sensor Delivers Precision in the Smallest Spaces

Features the smallest LED sensor on the market

Florence, Kentucky (Jan. 17, 2020) — Balluff's new wafer mapping sensor, BOH00EZ, utilizes a highly precise photoelectric sensor for quick and reliable detection of semiconductor wafers and slotting errors in FOUPS – front opening unified pods. Especially designed for use with extremely thin end effectors, it features an extremely controlled and focused light spot, allowing it to detect wafers even just a few μm thick with extreme precision.

Based on photoelectric Micromote technology, it features the smallest LED sensor on the market in an impressively small sensor head – measuring in at just 2.4 x 1.5 x 7 mm. This allows it to deliver precision in even the smallest spaces.

In addition to wafer mapping, this sensor delivers capabilities that can be used for a variety of applications that require through beam sensors in a small area, such as Life Science and Food and Beverage applications.

Key features:

- Multi-functional sensor head
- Smallest LED sensor on the market
- Very compact, extremely flexible sensor cable
- Flexible adaptation to the respective application using an external amplifier

Learn more at: www.balluff.com

About Balluff Inc.

Balluff Inc. is the U.S. subsidiary of Balluff GmbH, Neuhausen, Germany. Balluff is a leading supplier of networked IO-Link control system architectures that unlock the potential of the IIoT and Industry 4.0. Balluff offers a wide range of intelligent IO-Link and industrial Ethernet sensors in a variety of technologies including inductive, photoelectric, capacitive, and magnetic as well as magnetostrictive linear position sensors, magnetic tape linear encoders, industrial RFID systems, and industrial vision systems. Balluff provides cost-saving, process-enhancing solutions to machine builders and manufacturers to control, regulate, automate, assemble, position, and monitor manufacturing, assembly, and packaging sequences. Industries served include: automotive, packaging, food processing, beverages, tire, primary metals, conventional and alternative energy, semiconductor, plastics, and fluid power.